XILINX®

August 3, 2000

Product Change Notification PCN00003

A change in the die-attach material for all thermally enhanced BGA packages.

Subject:	Product Change Notification (PCN00003). “A change in the die-attach material for all thermally enhanced BGA packages.
Products Affected:	All packages assembled as SBGA or VBGA.
Change Description:	The die-attach material for all thermally enhanced BGA packages is being changed from QMI-595 to Hitachi EN4900 (or AMK-02 - Amkor's internal part number).
Qualification Data:	Reference qualification data.
Reason For Change:	This change is being made for better product reliability and for process improvement.
Key Dates:	Products assembled starting with date code 0044.
Response:	No response to this notification is required. Requests for additional data or support should be made within 90 days of notification. Please address any other questions you may have via e-mail at “pcn@xilinx.com”, or directly by fax at (408) 559-1368.